



Fig. 4 Sealing leads into a high temperature sensor using Ceramabond 569

Standing the heat

Specially developed from *Ceramabond 503* to withstand high temperatures in service is *Aremco Ceramabond 569*. This adhesive which is easy to dispense cures at room temperature, thus being suitable for use in situations where it would not be possible to apply a heat-cure, as in the case of sealing internal leads in a high temperature sensor (Fig. 4). *Ceramabond 569* is claimed to have good high temperature dielectric properties and temperature resistance to 1650°C.

The adhesive is available from: *The Meclec Company, 5/6 Towerfield Close, Shoeburyness, Essex, SS3 9QP, England.*

Ethereal quality

The introduction of an ether-based starch adhesive, *Monatex D.4633*, for use on high-speed glass bottle labelling machines, such as Krones, Jagenberg, or similar turret machines is announced by Monarch Adhesives Limited, UK. The company claim that the clean running ability, and high mileage figures obtained with this product make it highly economical in use, both from the cost per bottle labelled and from machine utilization considerations — provided it is used on bottles which will be kept at temperatures above 0°C. *Monatex D.4633* is packed in heavy duty polyethylene containers into which it is possible to place the pumping unit of the labelling machine directly.

Monarch Adhesives Limited,

Schoolfield Road, West Thurrock, Essex, RM16 1HR, England.

Electrically insulating epoxy

Designed for bonding substrates in microelectronic packages, *EPO-TEK H65*, is a black electrically-insulating epoxy. Due to its thermal conductivity it can also be used for binding two materials which have dissimilar coefficients of expansion, such as alumina to aluminium, and also, being semi-flexible is claimed to pass thermal shock in the range -55°C to 150°C. It will adhere to ferrous, non-ferrous, glass and ceramic surfaces and to semiconductor materials and, being in the form of a thixotropic paste, it can be applied using mechanical dispensing equipment or by syringe, spatula, and screen printing techniques. After application it will cure at 150°C in 30 min and thereafter can withstand temperatures, intermittently applied, up to 300°C.

Preview

The following is a preview of some forthcoming events — conferences, exhibitions — arranged in chronological order. Further details can be obtained from the address given at the end of each item. A full list of future meetings is given in the Calendar.

The Adhesion Society will be holding a short course on *Adhesion* at The Hilton Hotel, Mobile, Alabama, USA, on 20 and 21 February 1982. The course will be in conjunction with the Annual Meeting of the Society at the same location.

Further details are available from: *Dr K.C. Stueben, Union Carbide Corporation, Coatings Materials Division, PO Box 670, Bound Brook, NJ 08805, USA.*

The second Intercontinental SAMPE Conference, sponsored by the European Chapter of SAMPE (The Society for the Advancement of Material and Process Engineering) will be held in Stresa, Italy, on 8-10 June 1982. The theme of the meeting will be *Composite Materials and Special Bondings — contributions and possibility of application in the aerospace and transport sector.*

A trial kit (costing \$20) or additional information can be obtained from: *Sales Department, Epoxy Technology Incorporated, PO Box 567, Billerica, MA 01821, USA.*

Electrically conductive epoxy

Elecolit 312, recently launched by Industrial Science Limited, for use in 'chip bonding', and for lead terminations, conductive paths, and circuit assembly and repairs, is a single-component silver-filled epoxy adhesive, ready for use as supplied. It is claimed to exhibit both electrical and thermal conductivity, have a shelf-life of nine months at room temperature, and to cure at 100°C (faster curing can be achieved at higher temperatures).

Further details of the product are available from: *Industrial Science Limited, Leader House, 117/120 Snargate Street, Dover, Kent, CT17 9DB, England.*

A call for papers has already been issued from the European SAMPE Chairman: *Mr G. Jube, Aerospatiale, 37 Boulevard de Montmorency, 75781 — Paris (CEDEX 16) — France.*

Further details of the conference are available from: *Marge Smith, SAMPE, PO Box 613, Azusa, CA 91702, USA.*

The Plastics and Rubber Institute are organizing a three-day International Conference on polymer and latex emulsions entitled *Polymer Latex II* to take place at the Institution of Electrical Engineers, Savoy Place, London, England, on 15-17 June 1982. It is hoped that new information relating to polymer lattices, whether plastics or rubber, natural or synthetic, will be presented. Papers are anticipated to cover: emulsion polymerization and manufacture; properties; testing and characterization; and applications and processes. The latter will include: paints and industrial finishes; paper coating; surface coatings; and adhesives and binders.

The call for papers has already